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**Semiconductor devices – Micro-electromechanical devices –
Part 44: Test methods for dynamic performances of MEMS resonant electric-
field-sensitive devices**

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SEMICONDUCTOR DEVICES – MICRO-ELECTROMECHANICAL DEVICES –

Part 44: Test methods for dynamic performances of MEMS resonant electric-field-sensitive devices

1 Scope

This part of IEC 62047 describes terminology, definitions and test methods that are used to evaluate and determine the dynamic performance of MEMS (Micro-Electromechanical Systems) resonant electric-field-sensitive devices. It also specifies sample requirements and test equipment for dynamic performances of MEMS resonant electric-field-sensitive devices. The statements made in this document are also applicable to MEMS resonant electric-field-sensitive devices with various driving mechanisms such as electrostatic, electrothermal, electromagnetic, piezoelectric, etc.

2 Normative references

There are no normative references in this document.